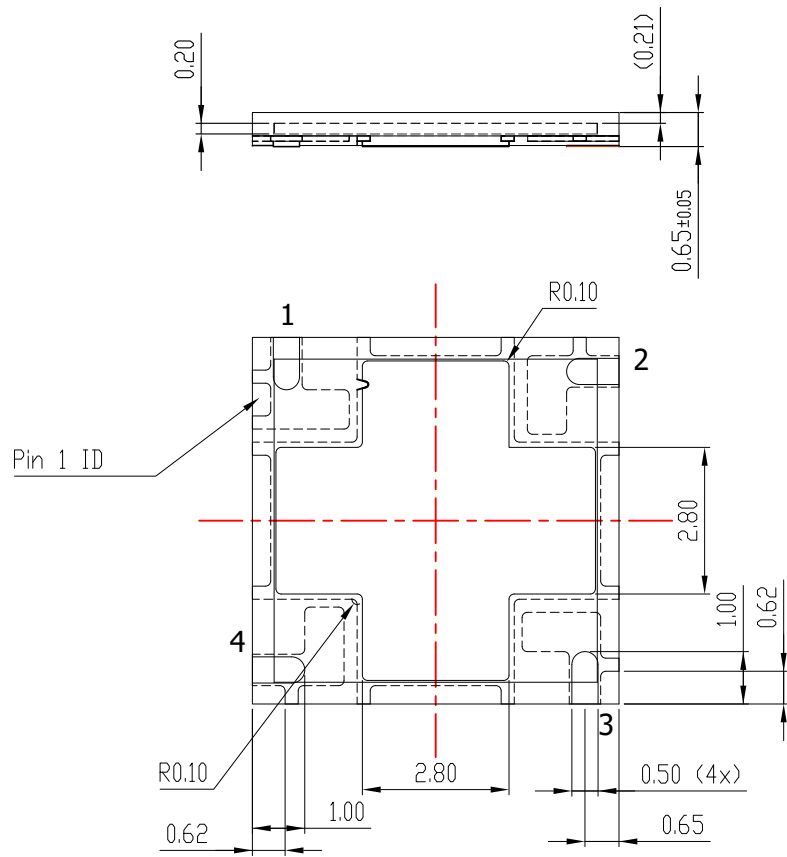


Side View Scale: 10 : 1

Top View Scale: 10 : 1

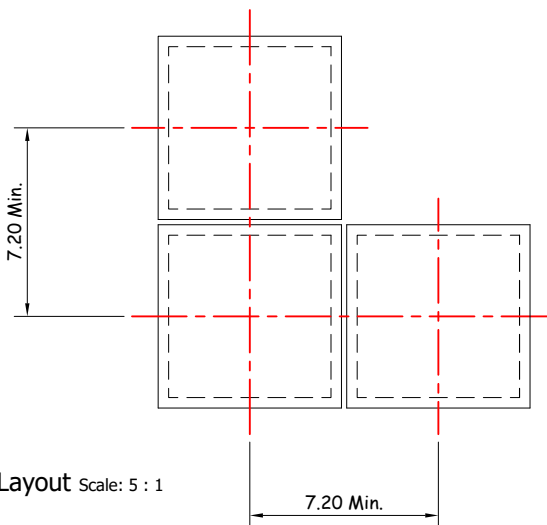
Pin Assignment	
Pin #	Description
1	P-Anode
2	F-Fast Output
3	N-Cathode
4	No Connect

DATE	28 June 2017	REVISION	C	SCALE:	10 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					1 of 6
DWG. NO:	SND0174	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFC-600xx-SMT-C1					
PROJECTION:					



Bottom View Scale: 10 : 1

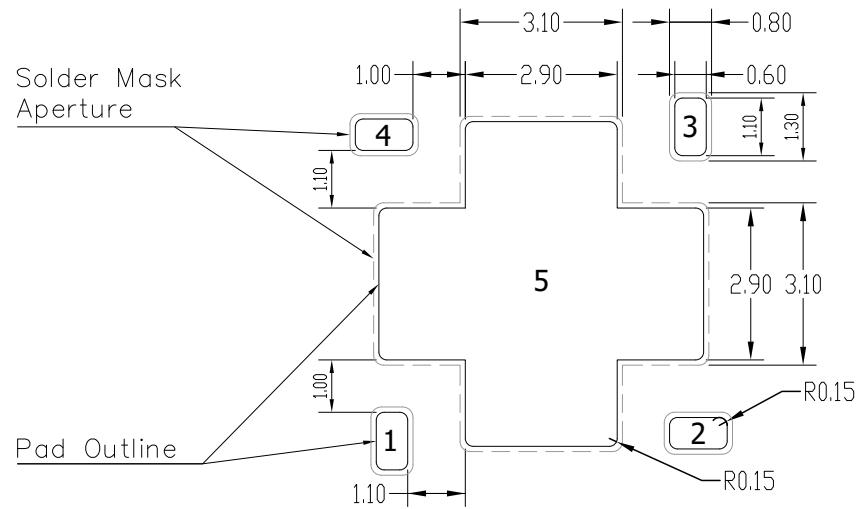
DATE	28 June 2017	REVISION	C	SCALE:	10 : 1
SensL Technologies Ltd					Sheet
www.sensl.com					2 of 6
DWG. NO:	SND0174	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFC-600xx-SMT-C1					
PROJECTION:					



Tiling Layout Scale: 5 : 1

NOTE: Alignment and placement tolerances depend on the accuracy of the equipment used in the assembly process.

DATE	28 June 2017	REVISION	C	SCALE	5 : 1
SensL Technologies Ltd www.sensl.com				Sheet 3 of 6	
DWG. NO:	SND0174	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: <b>MicroFC-600xx-SMT-C1</b>					
PROJECTION:					



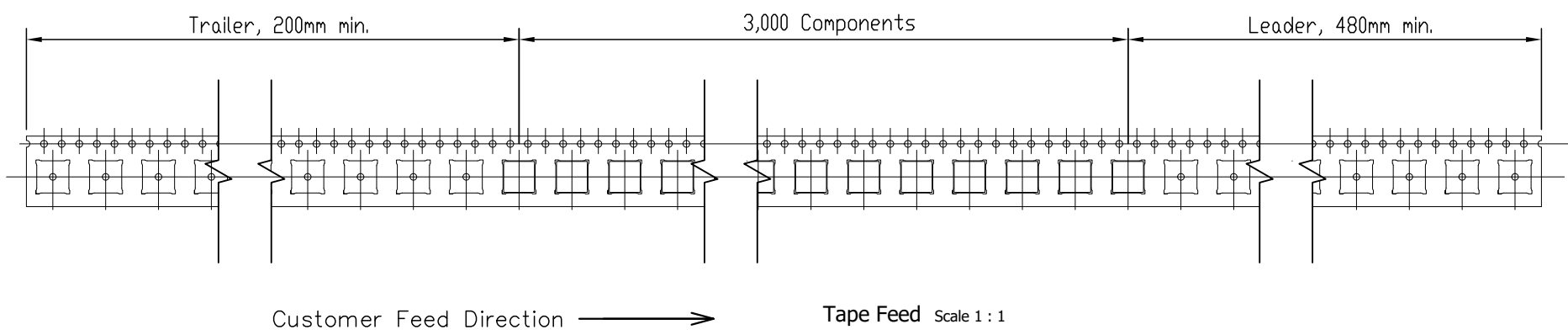
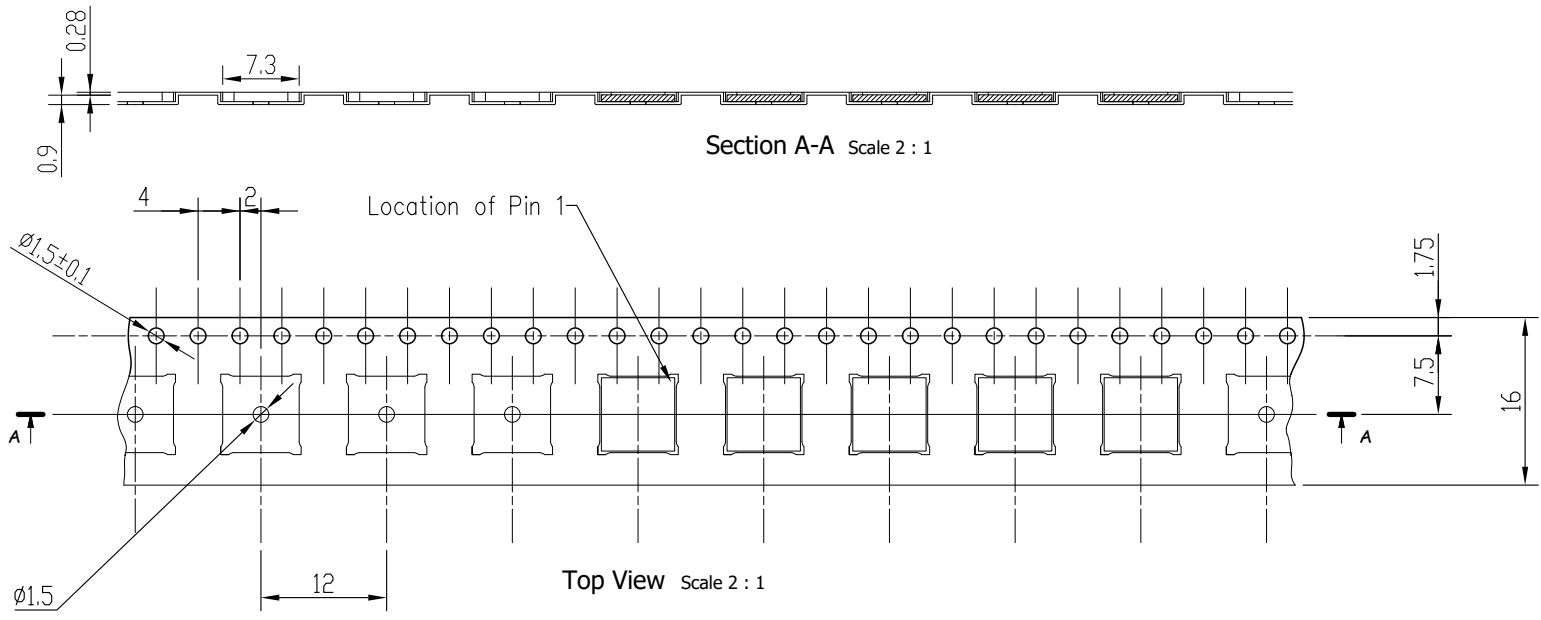
### Recommended PCB Solder Footprint

Scale: 10 : 1

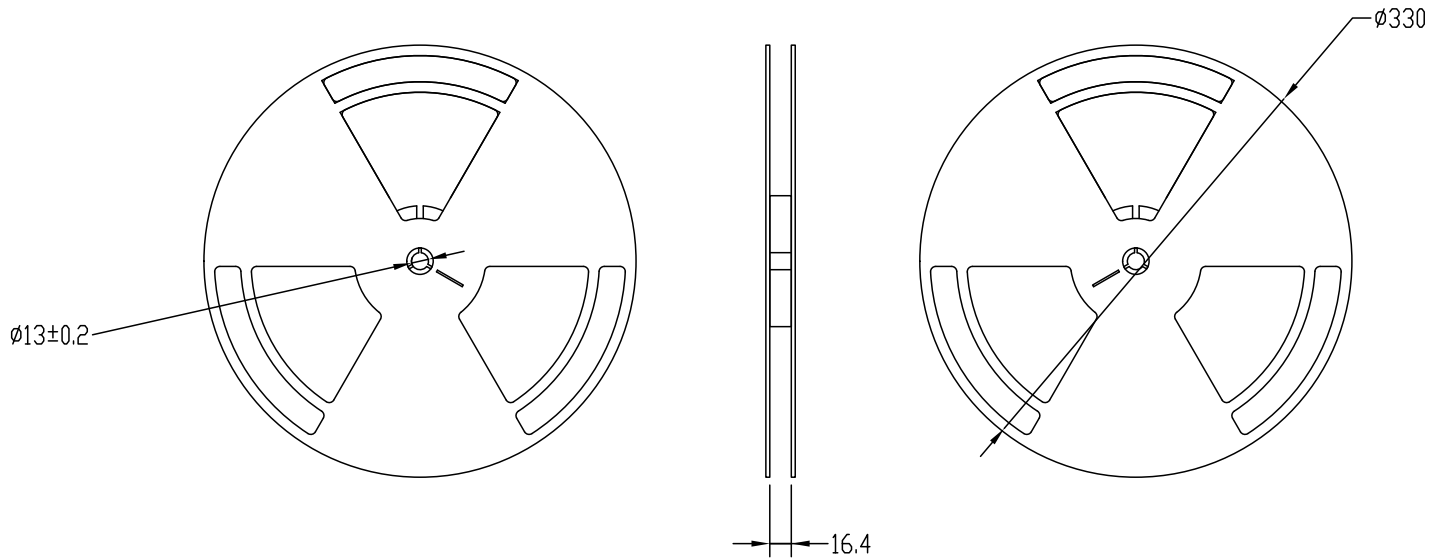
NOTE: No Connect (NC) pin 4 should be soldered to PCB, this pin can be connected to ground but it can also be left floating without affecting the dark noise.

Recommend that NC pin 5 paddle is not soldered to the PCB and left floating to achieve optimal soldering on pins 1 to 4. Care must be taken to ensure that no electrical contacts on the PCB, such as vias, short out on the paddle if using the area underneath for routing. If it is desired to solder pin 5 to the PCB, for example to heatsink or ground the paddle, please consult your contract manufacture for their solder recommendations based on their equipment and capabilities.

DATE	28 June 2017	REVISION	C	SCALE:	10 : 1
SensL Technologies Ltd www.sensl.com					Sheet 4 of 6
DWG. NO:	SND0174	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: <b>MicroFC-600xx-SMT-C1</b>					
PROJECTION:					



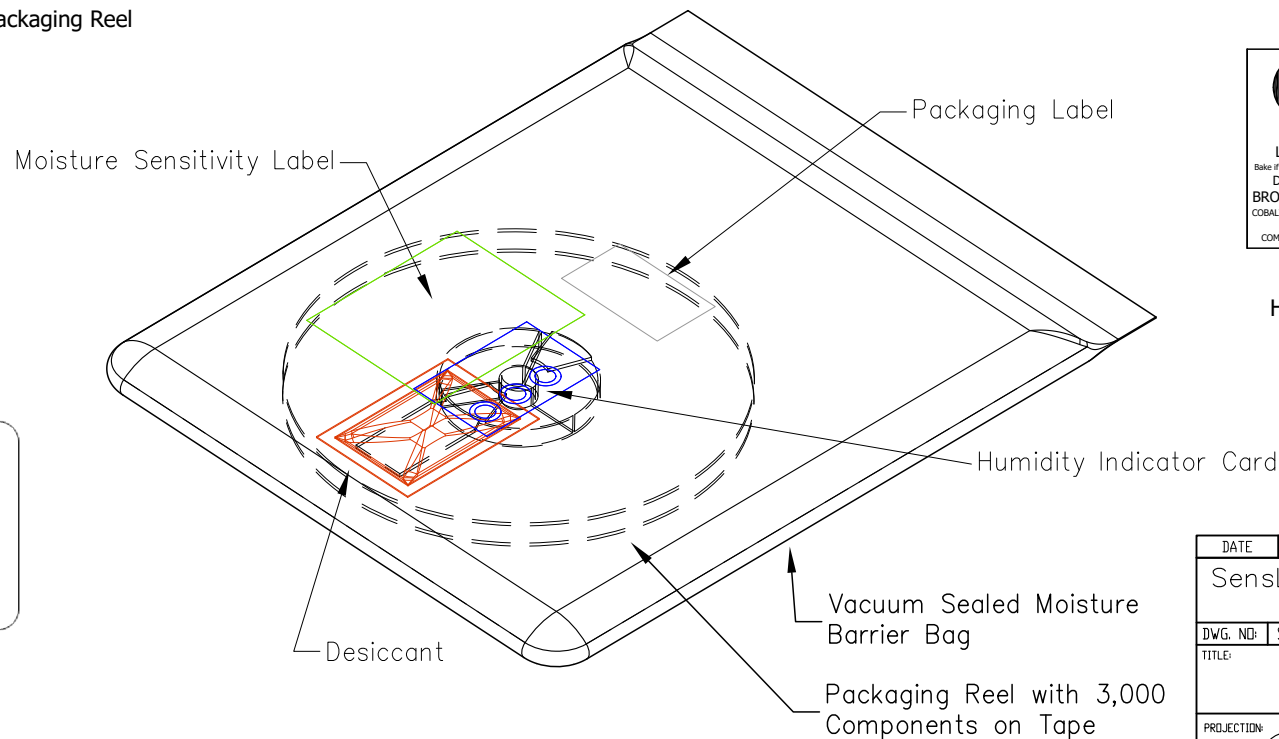
DATE	28 June 2017	REVISION	C	SCALE	Shown
SensL Technologies Ltd					Sheet
www.sensl.com					5 of 6
DWG. NO:	SND0174	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE:					
MicroFC-600xx-SMT-C1					
PROJECTION:					



Details of Packaging Reel

	<b>CAUTION</b>	<b>3</b>
<b>MOISTURE SENSITIVE DEVICES</b>		
1. Calculated shelf life in sealed bag: 24 months at <math>\le 40^{\circ}\text{C}</math> and <math>\le 90\%</math> relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C <small>If blank, see adjacent bar code label</small>		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>168</u> hours of factory		
conditions: <math>\le 30^{\circ}\text{C}</math> @ 90% RH, or		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads >10% for level 2a - 5s devices or >60% for level 2 devices when read at $23 \pm 5^{\circ}\text{C}$		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: <u>20 Mar. 2014</u> <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

Details of Moisture Sensitivity Label



5%	10%	60%
<b>LEVEL 2A-5A PARTS</b>		<b>LEVEL 2 PARTS</b>
Bake if 10% IS NOT BROWN and 5% IS AZURE		Bake parts if 60% IS NOT BROWN
<b>DOU YEE ENTERPRISES</b>		
<b>BROWN-DRY AZURE-WET</b>		
<b>COBALT FREE HUMIDITY INDICATOR CARD</b>		
AVOID METAL CONTACT		
COMPLIES WITH IPC/JEDEC J-STD-033		<b>H16 5 4 3 2 1</b>

Humidity Indicator Card

<b>sensl</b> <small>sense light</small>
<b>Part#: MICROFC-60035-SMT</b>
<b>Revision: C1</b>
<b>Lot#: E1234-35</b>
<b>Lot#</b>
<b>Quantity: 3000</b>

Sample Packaging Label

DATE	28 June 2017	REVISION	C	SCALE	Not to Scale
SensL Technologies Ltd www.sensl.com					Sheet 6 of 6
DWG. NO:	SND0174	DO NOT SCALE	ALL DIMENSIONS IN MM		
TITLE: <b>MicroFC-600xx-SMT-C1</b>					
PROJECTION:		<b>sensl</b> <small>sense light</small>			